

PCBSupplies CSN Tin Process

Description:

The PCBSupplies CSN Tin Process incorporates a unique patented “organic metal” to produce an Immersion Tin deposit that exhibits outstanding solderability. The Tin deposit retains solderability after 3 Reflow and 1 solder wave process sequences. The process is easy to control and can be used in immersion or flood installations.

Benefits:

- Multiple soldering possibilities.
- Excellent for SMD technology.
- Attractive white / grey finish.
- Economical.
- Long bath life.
- Simple control.
- 0.6 - 0.8 micron pure Tin desposit.

Application:

- (a) Thoroughly Degrease your PCB
 - (b) Double rinse. Remove ALL degreaser, avoid touching the board.
 - (c) Optional - Micro etch 1-2 Mins @ 20 - 25°C. Gives a brighter finish and removes minor imperfections from the board (PCBSupplies 1174 used at 100 grammes per litre)
 - (d) Double rinse. Remove ALL micro etch, avoid touching the board.
 - (e) PCBSupplies CSN Tin Process. 1 Min @ 20 - 25°C
 - (f) Double rinse.
- Use PVC or Polypropelene Tanks and PTFE heaters
 - Lateral agitation recommended.

Handling precautions:

PCBSupplies PCBSupplies CSN Tin Process - Harmful and Corrosive. Contains Thiourea.

Heath and Saftey:

See Crownhill_CSN7001MSDS Supplied with product.

Disposal of Spent Solutions:

PCBSupplies CSN Tin Process - Toxic material containing Heavy Metals. Use registered waste disposal agent.

Warranty:

All reasonable endeavours have been made to ensure that the information contained in this data sheet is accurate, but it is submitted on the express condition that Crownhill Associates Ltd. shall be under no liability whatsoever in respect thereof or for any loss, injury, damage or liability of whatsoever nature arising, suffered or incurred as a consequence of its use.